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PATENT

THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Kumar et al.	Examiner: B. Talbot
Serial No. 09/903,114	Group Art Unit: 1762
Filed: July 11, 2001	
For: THERMAL PROCESSING SYSTEM AND METHODS FOR FORMING LOW-K DIELECTRIC FILMS SUITABLE FOR INCORPORATION INTO MICROELECTRONIC DEVICES	Docket No. FSI0006/US/2

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

I CERTIFY THAT ON Jan 23, 2004, THIS PAPER IS
BEING DEPOSITED WITH THE U.S. POSTAL SERVICE AS FIRST
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FEE AMENDMENT, MAIL STOP ISSUE FEE, COMMISSIONER FOR
PATENTS, P.O. Box 1450, ALEXANDRIA, VA 22313-1450

Paula J. Breeden
PAULA J. BREEDEN

AMENDMENT AFTER ALLOWANCE UNDER 37 CFR 1.312

Dear Sir or Madam:

This Amendment is filed pursuant to 37 C.F.R. § 1.312 since it is filed after the mailing of the Notice of Allowance for the above-referenced Patent Application, which was mailed January 8, 2004.

This Amendment is believed to be timely because it is filed before the payment of the issue fee.

It is believed that no fee is required in filing this Amendment. However, if any fee is required, please charge the appropriate fee to the Kagan Binder Deposit Account No. 50-1775 and notify us of the same.